



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	RDS(ON) Max	I _D T _A = +25°C
20V	$24m\Omega$ @ $V_{GS} = 4.5V$	6.2A
200	$32mΩ @ V_{GS} = 2.5V$	0.2A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- **Power Management Functions**
- Backlighting

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

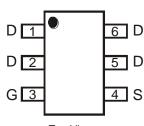
Mechanical Data

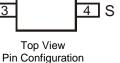
- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.013 grams (Approximate)

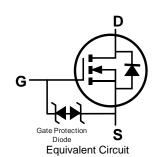
TSOT26



Top View







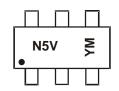
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2026UVT-7	TSOT26	3,000/Tape & Reel
DMN2026UVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



N5V = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014)M = Month (ex: 9 = September)

Date Code Key

Year	2014	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D	E		F		G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	±10	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	I _D	6.2	Α
Maximum Body Diode Forward Current (Note 6)	Is	2	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	20	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	1.15	W	
Thermal Decistores Junction to Ambient (Note 5)	Steady state		107	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	76	C/VV	
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	1.75	W	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state		75	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	50		
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	16			
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

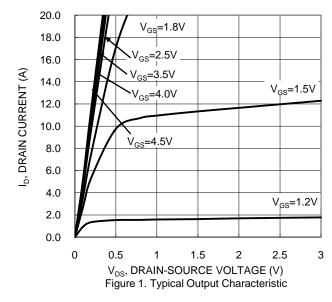
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	, ,		71				
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	V _{DS} = 20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.4	_	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		-	18	24	mΩ	$V_{GS} = 4.5V, I_D = 6.2A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	21	32	11152	$V_{GS} = 2.5V, I_D = 5.2A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.3A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	887	_		10/1/	
Output Capacitance	Coss		91	_	pF	$V_{DS} = 10V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C_{rss}	_	37	_		I = 1.0WI IZ	
Gate Resistance	R_{g}	1	191	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_{g}	I	10	_			
Total Gate Charge (V _{GS} = 8V)	Q_{g}	1	18.4	_	nC	V _{DS} = 10V, I _D = 6.5A	
Gate-Source Charge	Q_{gs}		1.3	_	110	VDS = 10V, ID = 0.3A	
Gate-Drain Charge	Q_{gd}	_	1.8	_			
Turn-On Delay Time	t _{D(ON)}	_	53	_			
Turn-On Rise Time	t _R	_	66	_	ns	$V_{DS} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	619	_	115	$R_G = 6\Omega$, $R_L = 10\Omega$, $I_D = 1A$	
Turn-Off Fall Time	t _F	_	197	_			
Reverse Recovery Time	t _{RR}	_	119	_	ns	$I_F = 4A$, di/dt = 100A/ μ s	
Reverse Recovery Charge	Q_{RR}		96		nC	$I_F = 4A$, di/dt = 100A/ μ s	

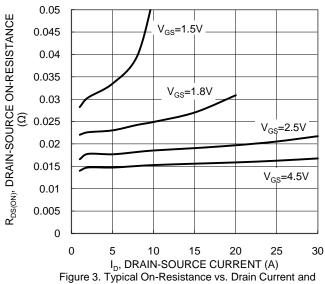
Notes:

- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.

DIODES

DMN2026UVT





Gate Voltage

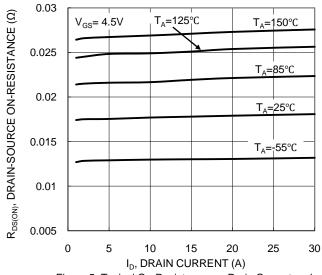
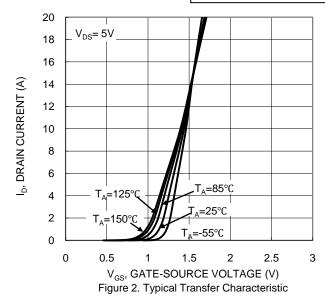
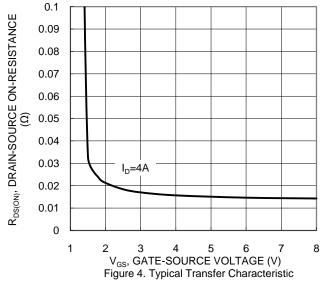


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





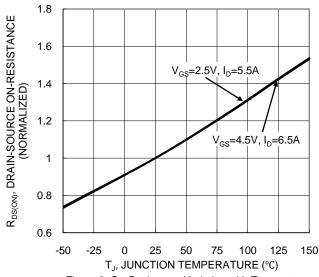
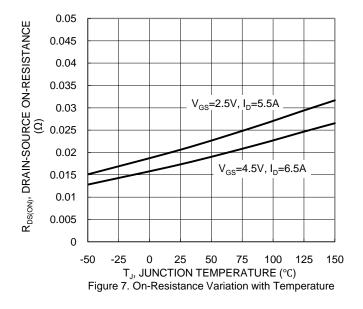
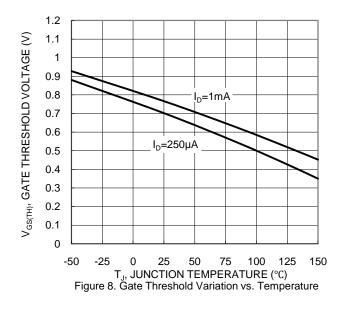
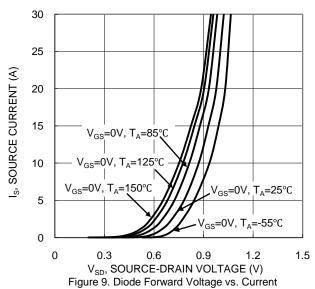


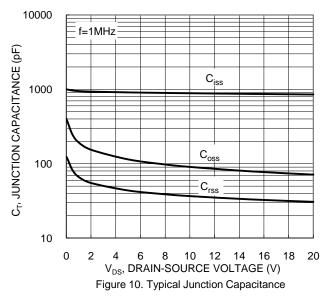
Figure 6. On-Resistance Variation with Temperature

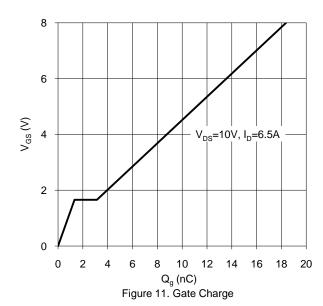


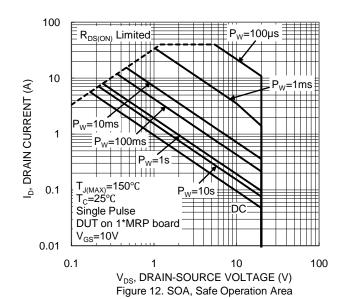




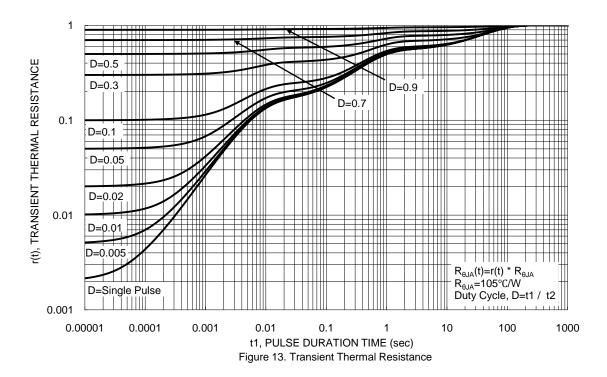






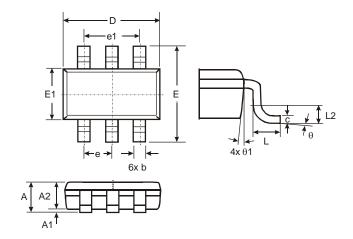






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

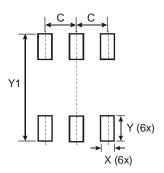


TSOT26								
Dim	Min Max Typ							
Α	_	1.00	_					
A1	0.01	0.10						
A2	0.84	0.90						
D			2.90					
Е			2.80					
E1	_	_	1.60					
b	0.30	0.45	_					
С	0.12	0.20	_					
е	_	_	0.95					
e1			1.90					
L	0.30	0.50						
L2			0.25					
θ	0°	8°	4°					
θ1	4°	12°	_					
All D	All Dimensions in mm							



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
Х	0.700
Υ	1.000
Y1	3.199

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